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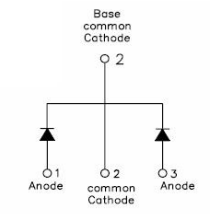
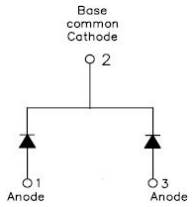
ST30200C/STB30200C SCHOTTKY RECTIFIER

Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features

- 150 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Trench MOS Schottky technology
- Terminals finish: Tin Lead-free plated
- This is a Pb − Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

ST30200C	STB30200C
	
	
TO-220AB	D^2PAK

Maximum Ratings@T_C=25°C unless otherwise specified

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	-	200	V
Average Rectified Forward Current	$I_{F\ (AV)}$	Tc=113°C, In DC	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I_{FSM}	8.3ms, Half Sine pulse	200	A

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RoHS

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	V_{F1}	@ 5A, Pulse, T_J = 25 °C @ 10A, Pulse, T_J = 25 °C @ 15A, Pulse, T_J = 25 °C	0.70 0.78 0.81	- - 1.10	V
	V_{F2}	@ 5A, Pulse, T_J = 125 °C @ 10A, Pulse, T_J = 125 °C @ 15A, Pulse, T_J = 125 °C	0.56 0.61 0.68	- - 0.72	V
Reverse Current(Per Leg)*	I_{R1}	@V_R = rated V_R, T_J = 25℃	0.0005	0.16	mA
	I_{R2}	@V_R = rated V_R, T_J = 125℃	1	12	mA
Junction Capacitance	C_T	@V_R = 5V, T_C = 25 °C f_{SIG} = 1MHz	300	-	pF

* Pulse width < 300 μs, duty cycle < 2%

Thermal-Mechanical Specifications:

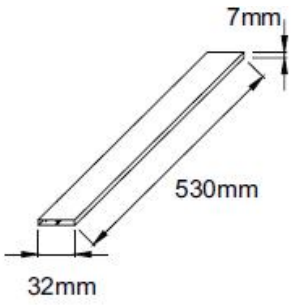
Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +150	°C
Storage Temperature	T_{stg}	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case(Per Leg)	$R_{\theta JC}$	DC operation	2.2	°C/W

Tube Specification

Device	Package	Weight	Shipping
ST30200C	TO-220AB	2.0	50pcs / tube
STB30200C	D^2 PAK	1.85	800pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Tube Specification(TO-220AB)



Ratings and Characteristics Curves

Fugre1
Typical Forward Characteristics

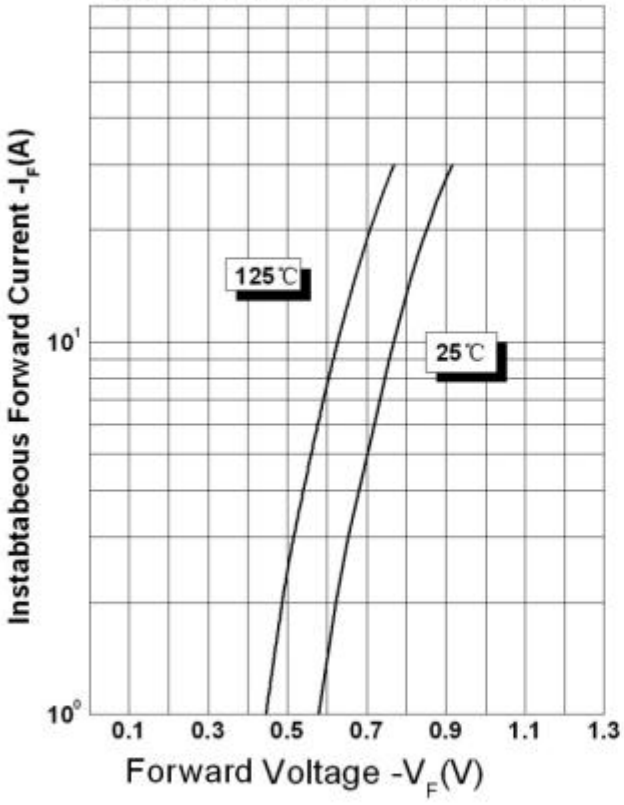


Figure 2
Typical Reverse Characteristics

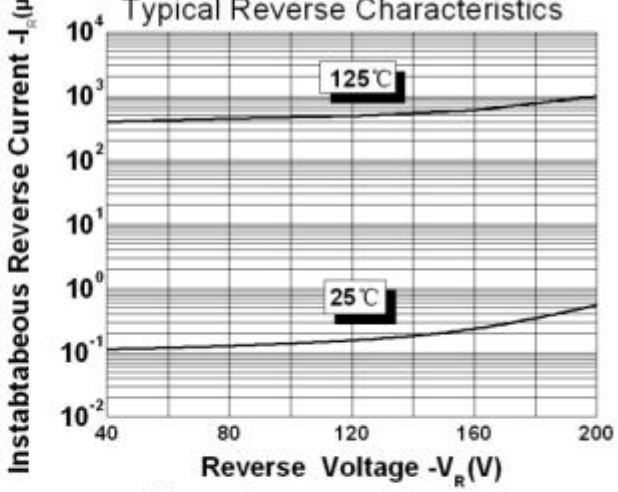
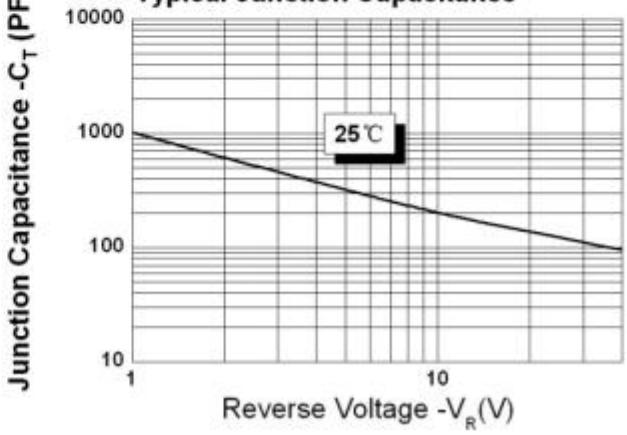


Figure 3
Typical Junction Capacitance



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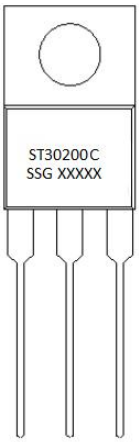
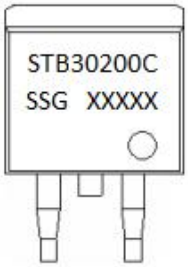
Marking Diagram



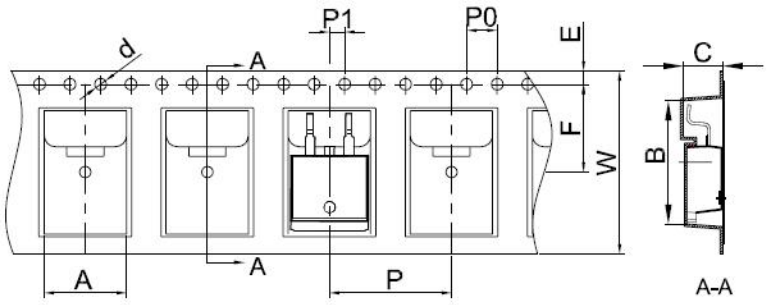


Where XXXXX is YYWWL

ST	= Device Type
B	= Package type
30	= Forward Current (30A)
200	= Reverse Voltage (200V)
C	= Configuration
SSG	= SSG
YY	= Year
WW	= Week
L	= Lot Number

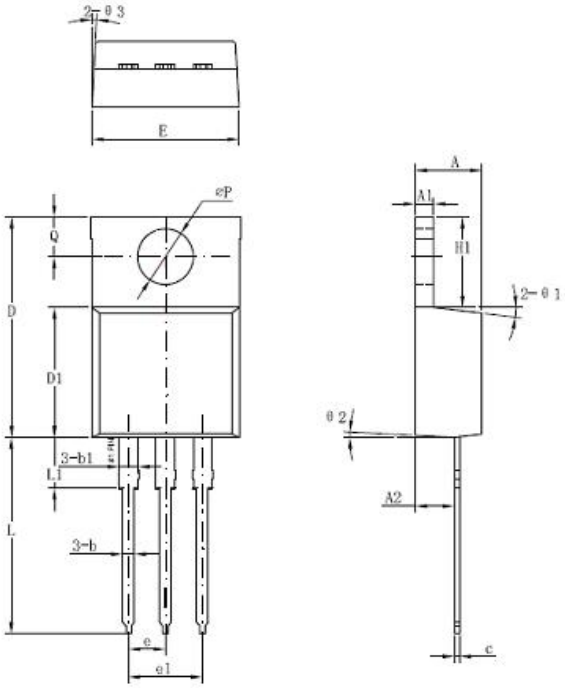
Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification D2PAK



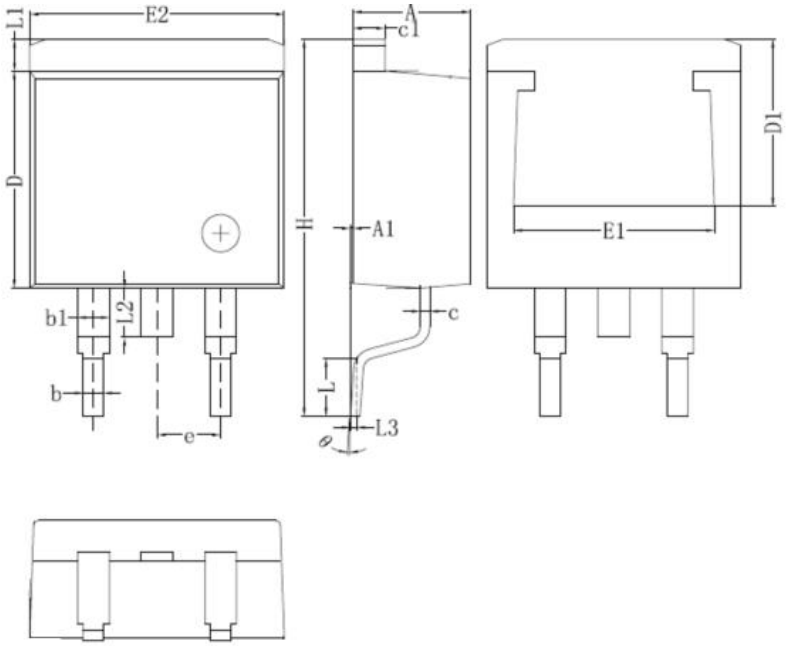
SYMBOL	Millimeters	
	Min.	Max.
A	10.70	10.90
B	16.03	16.23
C	5.11	5.31
d	1.45	1.65
E	1.65	1.85
F	11.40	11.60
P0	3.90	4.10
P	15.90	16.10
P1	1.90	2.10
W	23.90	24.30

Mechanical Dimensions TO-220AB



Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	3.56	-	4.83
A1	0.51	-	1.4
A2	2.03	-	2.92
b	0.38	-	1.02
b1	1.14	-	1.78
c	0.31	-	0.61
D	14.22	-	16.51
D1	8.38	-	9.42
E	9.65	-	10.67
e	-	2.54	-
e1	-	5.08	-
H1	5.84	-	6.86
L	12.7	-	14.73
L1	-	-	6.35
ΦP	-	3.56	-
Q	2.54	-	3.43

Mechanical Dimensions D²PAK



Symbol	Dimensions in millimeters	
	Min.	Max.
A	4.06	4.83
A1	0	0.26
b	0.51	0.99
b1	1.14	1.78
c	0.31	0.74
c1	1.14	1.65
D	8.38	9.65
D1	6.4	
E1	6.22	
E2	9.65	10.67
e	2.54BSC	
H	14.6	15.88
L	1.78	2.8
L1	-	1.68
L2	-	2.2
L3	0.255BSC	
Θ	0	8°

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